

# BigTwin SuperServer SYS-221BT-HNC9R



More details here

## Key Applications

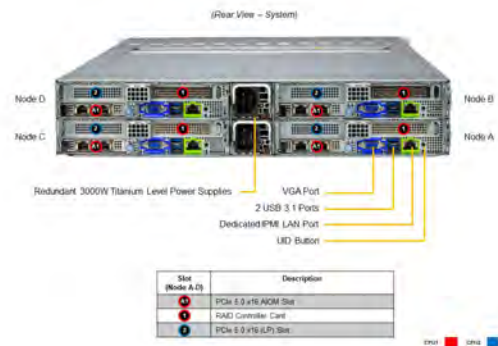
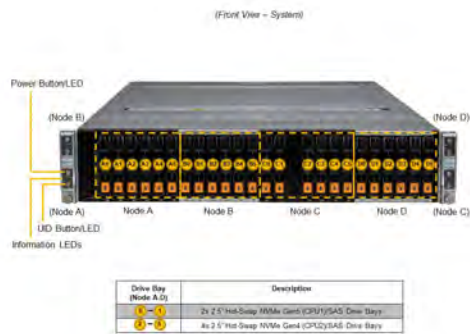
Mission Critical HPC, Virtualized Big Data Analytics, High-Density Storage RAID Array,

## Key Features

- Socket E (LGA 4677) support 4th Gen Intel® Xeon® Scalable processors;
- Intel® C741;
- Up to 16 DIMMs ECC DDR5 Slots;
- Internal PCIe 4.0 x8 for 2 M.2 NVMe support onboard; 1 PCIe 5.0 x16 (LP) slot; Tool-less support; Optional M.2 NVMe Boot Controller via SCC-A2NM2241G3-B1;
- Network connectivity via AIOM (OCP 3.0 compliant);
- 6 hot-swap 2.5" drive bays (2x PCIe 5.0 NVMe and 4x PCIe 4.0 NVMe/SAS); Built-in SAS3 Support via Broadcom 3908; IT Mode;
- Liquid Cooling Support; 4 cooling fans per 2U enclosure, 16K RPM; Shared Cooling Design, Counter-Rotating;
- 3000W Redundant Power Supplies Titanium Level (96%+); Shared Power Design;



<b>Form Factor</b>	2U Rackmount Enclosure: 449 x 88 x 730mm (17.68" x 3.47" x 28.75") Package: 626 x 248 x 1150mm (24.65" x 9.76" x 45.28")
<b>Processor</b>	4th Gen Intel® Xeon® Scalable processors Dual Socket LGA 4677 (Socket E) supported Intel Xeon CPU Max Series with high bandwidth memory (HBM) (Supports up to 350W TDP CPUs (Liquid Cooled), Supports up to 205W TDP CPUs (Aircooled)*, *CPUs (air cooled) with TDP over 205W are only supported under specific conditions. Contact customer support for details.)
<b>Drive Bays</b>	6x 2.5" hot-swap NVMe/SAS drive bays; Optional RAID support via Broadcom® 3908 AOC
<b>Expansion Slots</b>	1 PCIe 5.0 x16 LP slot(s)
<b>On-Board Devices</b>	SAS: SAS3 (12Gbps) via Broadcom® 3908; RAID 0, 1, 5, 6, 10, 50 support Chipset: Intel® C741 Network Connectivity: Via AIOM IPMI: Support for Intelligent Platform Management Interface v.2.0 IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
<b>Input / Output</b>	LAN: 1 RJ45 Dedicated BMC LAN port USB: 2 USB 3.1 port(s) (2 rear) Video: 1 VGA port(s) Others: 2x M.2 for boot drive or caching M.2 form factor: NVMe double-sided 22x110mm Note: Enterprise-grade M.2 only for caching application



System Cooling	4x 16K RPM Counter Rotating 8cm Fan(s) Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)
Power Supply	3000W 1U Redundant Power Supply Dimension (W x H x L): 45 x 40 x 480 mm
System BIOS	BIOS Type: AMI 32MB Flash ROM
Management	SuperDoctor® 5; Watch Dog; SUM; IPMI 2.0; KVM with dedicated LAN; SPM; Intel® Node Manager; SSM; SuperCloud Composer; Supemicro Out of Band (OOB) License (Included per Node)
PC Health Monitoring	FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment CPU: Monitors for CPU Cores, Chipset Voltages, Memory. 8+4 Phase-switching voltage regulator
Dimensions and Weight	Height: 3.47" (88 mm) Width: 17.68" (449 mm) Depth: 28.75" (730 mm) Gross Weight: 96.6 lbs (43.8 kg) Net Weight: 66.1 lbs (30 kg) Packaging: 9.76" (H) x 24.65" (W) x 45.28" (D) Available Color: Black front & silver body
Operating Environment	ROHS: RoHS Compliant Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -40°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 90% (Non-Condensing) Non-operating Relative Humidity: 5% to 95% (Non-Condensing)
Motherboard	<a href="#">Super X13DET-B</a>
Chassis	CSE-217BQ2-R3K04P